

Features

- High reliability
- General purpose leads
- Peak wavelength λp=880nm
- Mechanically and spectrally matched to the phototransistor
- Low forward voltage
- High radiant intensity

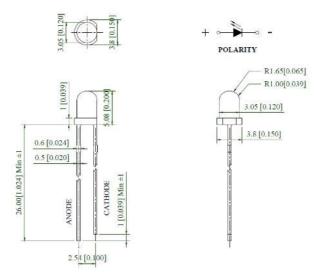
Applications

- Optoelectronic Switch
- IR Touch-Panel
- Industrial IR Equipment
- Consumer Electronics
- High Speed IR Communications

Description

- The infrared emitting diode (880nm) is a high intensity diode, molded in a blue transparent plastic package.
- The device is spectrally matched with silicon photodiode and phototransistor.

Package Dimensions in mm



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25 mm (.010 $^{\prime\prime}$) unless otherwise noted.

Figure 1. INL-3ABCMIR40 Package Dimensions



Absolute Maximum Rating at 25°C (Note 1)

| Product | Emission Color | P _d (mW) | I _F (mA) | I _{FP} * (A) | V _R (V) | T _{OP} (°C) | T _{ST} (°C) |
|---------------|-------------------|---------------------|---------------------|-----------------------|--------------------|----------------------|----------------------|
| INL-3ABCMIR40 | Infrared | 160 | 100 | 1 | 5 | -40°C~+80°C | -40°C~+85°C |

Notes

Electrical Characteristics $T_A = 25\%$ (Note 1)

| | | Emission | | V _F (V) | | λ(nm) | | | Viewing Angle | Ee(mW/sr) | |
|--|---------------|----------|---------------------|--------------------|-----|---------------|---------------|----|--------------------|-----------|------|
| | Product | Color | I _F (mA) | min | max | λ_{D} | λ_{P} | Δλ | 2 0 1/2 | min | typ. |
| | INL-3ABCMIR40 | Infrared | 20 | 1.0 | 1.6 | - | 880 | 45 | 40 | 8 | 10 |

Notes

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AllnGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

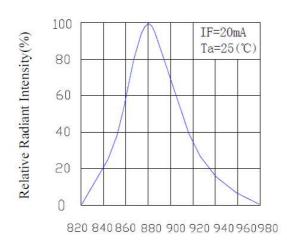
^{1.} Condition for IFP is pulse of 1/10 duty and 1kHz frequency

^{1.} Performance guaranteed only under conditions listed in above tables.



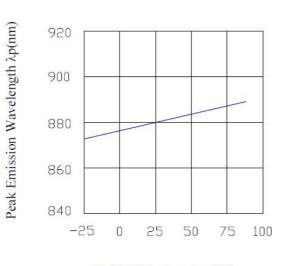
Typical Characteristic Curves

Spectral Distribution



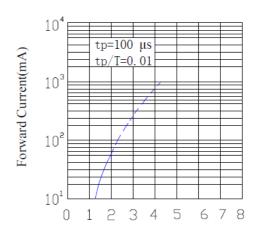
Wavelength λ(nm)

Peak Emission Wavelength & Ambient Temperature



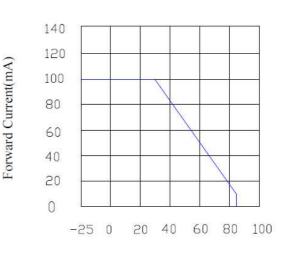
Ambient Temperature(°C)

Forward Current & Forward Voltage



Forward Voltage(V)

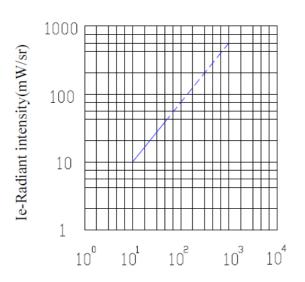
Forward Current & Ambient Temperature



Ambient Temperature(℃)

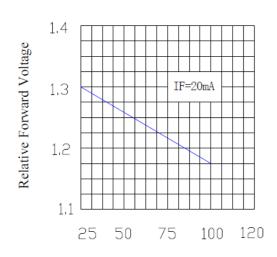


Relative Intensity & Forward Current



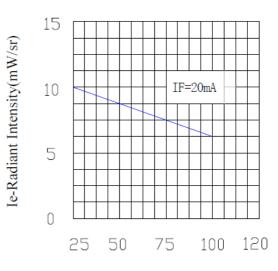
IF-Forward Current(mA)

Forward Voltage & Ambient Temperature(°C)



Ambient Temperature (°C)

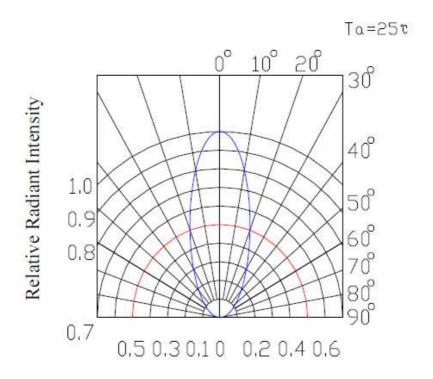
Relative Intensity & Ambient Temperature($^{\circ}$ C)



Ambient Temperature (°C)



Typical Characteristic Curves – Radiation Pattern

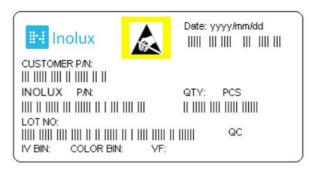


Ordering Information

| Product | Emission Color | Technology | Test Current I _F (mA) | Radiant Intensity Ee (mW/sr) (Typ.) | Forward Voltage V _F (V) (Typ.) | Orderable Part Number |
|---------------|-------------------|------------|-------------------------------------|---|--|--------------------------|
| INL-3ABCMIR40 | Infrared | AlGaAs | 20 | 10 | 1.3 | INL-3ABCMIR40 |



Label Specifications



Inolux P/N:

| I | N | | L | - | 3 | Α | ВС | MIR | 4 | 0 | | Х | Х | Х | Х |
|---|---------------|--|---------|---|------|-------------------|------------------|----------------|------|-------------------------|--|---|---|---|---|
| | | | Package | | Lens | Color | View Angle | | | Customized Stamp-off | | | | | |
| | Inolu mp 1 | | e | | stan | \ = dard nm | BC=Blue Clear | MIR = 880nm | 40 = | 40 deg. | | | | | |

Lot No.:

| Z | 2 | 0 | 1 | 7 | 01 | 24 | 001 |
|----------|---|-------------|----------|-----------|--------|--------|-----|
| Internal | | Year (2017 | Month | Date | Serial | | |
| Tracker | | 1Cai (2017) | , 2010,) | 141011611 | Date | Scriai | |





Reliability

| Item | Frequency/ lots/ samples/ failures | Standards Reference | Conditions | | |
|--|---|--------------------------------|---|--|--|
| Precondition | For all reliability monitoring tests according to JEDEC Level 2 | J-STD-020 | 1.) Baking at 85°C for 24hrs2.) Moisture storage at 85°C/60% R.H. for 168hrs | | |
| Solderability | 1Q/ 1/ 22/ 0 | JESD22-B102-B And CNS-5068 | Accelerated aging 155°C/ 24hrs Tinning speed: 2.5+0.5cm/s Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s | | |
| Resistance to soldering heat | | CNS-5067 | Dipping soldering terminal only Soldering bath temperature A: 260+/-5°C; 10+/-1s B: 350+/-10°C; 3+/-0.5s | | |
| Operating life test | 1Q/ 1/ 40/ 0 | CNS-11829 | 1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs | | |
| High humidity, high temperature bias | 1Q/ 1/ 45/ 0 | JESD-A101-B | Tamb: 85°C Humidity: 85% R.H., IF=5mA Duration: 1000hrs | | |
| High temperature bias | 1Q/ 1/ 20 | IN specs. | Tamb: 55°C IF=20mA Duration: 1000hrs | | |
| Pulse life test | 1Q/ 1/ 40/ 0 | | Tamb25°C, If=20mA,, Ip=100mA, Duty cycle=0.125 (tp=125 μ s,T=1sec) Duration 500hrs) | | |
| Temperature cycle | 1Q/ 1/ 76/ 0 | JESD-A104-A IEC 68-2-14, Nb | A cycle: -40 degree C 15min; +85 degree C 15min Thermal steady within 5 min 300 cycles 2 chamber/ Air-to-air type | | |
| High humidity storage test | 1Q/ 1/ 40/ 0 | CNS-6117 | 60+3°C 90+5/-10% R.H. for 500hrs | | |
| High temperature storage test | 1Q/ 1/ 40/ 0 | CNS-554 | 100+10°C for 500hrs | | |
| Low temperature storage test | 1Q/ 1/ 40/ 0 | CNS-6118 | -40+5°C for 500hrs | | |





Revision History

| Changes since last revision | Page | Version No. | Revision Date |
|-----------------------------|------|-------------|---------------|
| Initial Release | | 1.0 | 01-19-2019 |
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